



PROCESS CHANGE NOTICE PCN0114

ADDITIONAL WAFER FABRICATION SOURCE OF SUPPLY

Change Description:

Altera is adding Micron Technology's wafer fabrication facility located in Boise Idaho for its Configuration Device Flash Memory support.

Reason For Change:

Micron Technology has been selected as a second source because of their excellent wafer fabrication performance and their ability to accommodate Altera's high-volume demands.

Products Affected:

EPC4 devices.

Product Traceability and Transition Dates:

Devices assembled with the Micron Technology die are scheduled to begin shipping after November 1, 2001 and can be distinguished by the country of origin, "Taiwan", marked on the device (see PCN0113).

Contact:

For more information, please contact your local Altera sales representative. Qualification data will be available September 2001. Please contact the Altera Customer Quality Engineering Department at (408) 544-6933 for more details.